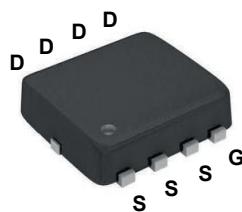
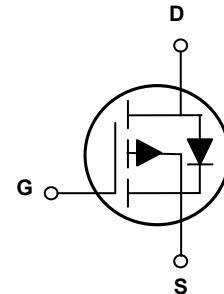


## Main Product Characteristics

BV <sub>DSS</sub>	-30V
R <sub>DS(ON)</sub>	19mΩ (max.)
I <sub>D</sub>	-30A



PPAK3x3



Schematic Diagram

## Features and Benefits

- Advanced MOSFET process technology
- Ideal for high efficiency switched mode power supplies
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery



## Description

The GSFP3019 utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supplies and a wide variety of other applications.

## Absolute Maximum Ratings (T<sub>A</sub>=25°C unless otherwise specified)

Parameter	Symbol	Max.	Unit
Drain-Source Voltage	V <sub>DS</sub>	-30	V
Gate-Source Voltage	V <sub>GS</sub>	±25	V
Drain Current-Continuous (T <sub>C</sub> =25°C)	I <sub>D</sub>	-30	A
Drain Current-Continuous (T <sub>C</sub> =100°C)		-19	
Drain Current-Pulsed <sup>1</sup>	I <sub>DM</sub>	-120	A
Single Pulse Avalanche Energy <sup>2</sup>	E <sub>AS</sub>	54	mJ
Single Pulse Avalanche Current <sup>2</sup>	I <sub>AS</sub>	-33	A
Power Dissipation (T <sub>C</sub> =25°C)	P <sub>D</sub>	27	W
Power Dissipation-Derate above 25°C		0.22	W/°C
Thermal Resistance, Junction-to-Ambient	R <sub>θJA</sub>	62	°C/W
Thermal Resistance, Junction-to-Case	R <sub>θJC</sub>	4.6	°C/W
Operating Junction Temperature Range	T <sub>J</sub>	-55 To +150	°C
Storage Temperature Range	T <sub>STG</sub>	-55 To +150	°C

**Electrical Characteristics** ( $T_J=25^\circ\text{C}$  unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
<b>On / Off Characteristics</b>						
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=-250\mu\text{A}$	-30	-	-	V
$\text{BV}_{\text{DSS}}$ Temperature Coefficient	$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	Reference to $25^\circ\text{C}$ , $I_{\text{D}}=-1\text{mA}$	-	-0.03	-	$\text{V}/^\circ\text{C}$
Drain-Source Leakage Current	$I_{\text{DSS}}$	$V_{\text{DS}}=-27\text{V}, V_{\text{GS}}=0\text{V}, T_J=25^\circ\text{C}$	-	-	-1	$\mu\text{A}$
		$V_{\text{DS}}=-24\text{V}, V_{\text{GS}}=0\text{V}, T_J=125^\circ\text{C}$	-	-	-10	$\mu\text{A}$
Gate-Source Leakage Current	$I_{\text{GSS}}$	$V_{\text{GS}}=\pm 20\text{V}, V_{\text{DS}}=0\text{V}$	-	-	$\pm 100$	nA
Static Drain-Source On-Resistance	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}}=-10\text{V}, I_{\text{D}}=-8\text{A}$	-	16	19	$\text{m}\Omega$
		$V_{\text{GS}}=-4.5\text{V}, I_{\text{D}}=-6\text{A}$	-	25	30	
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{GS}}=V_{\text{DS}}, I_{\text{D}}=-250\mu\text{A}$	-1.1	-1.6	-2.9	V
$V_{\text{GS}(\text{th})}$ Temperature Coefficient	$\Delta V_{\text{GS}(\text{th})}$		-	4	-	$\text{mV}/^\circ\text{C}$
Forward Transconductance	$g_{\text{fs}}$	$V_{\text{DS}}=-10\text{V}, I_{\text{D}}=-8\text{A}$	-	6.8	-	S
<b>Dynamic and Switching Characteristics</b>						
Total Gate Charge <sup>2,3</sup>	$Q_g$	$V_{\text{DS}}=-15\text{V}, I_{\text{D}}=-5\text{A}, V_{\text{GS}}=-4.5\text{V}$	-	11	17	nC
Gate-Source Charge <sup>2,3</sup>	$Q_{\text{gs}}$		-	3.4	6	
Gate-Drain Charge <sup>2,3</sup>	$Q_{\text{gd}}$		-	4.2	8	
Turn-On Delay Time <sup>2,3</sup>	$t_{\text{d}(\text{on})}$	$V_{\text{DD}}=-15\text{V}, R_{\text{G}}=6\Omega, V_{\text{GS}}=-10\text{V}, I_{\text{D}}=-1\text{A}$	-	5.8	11	nS
Rise Time <sup>2,3</sup>	$t_r$		-	18.8	36	
Turn-Off Delay Time <sup>2,3</sup>	$t_{\text{d}(\text{off})}$		-	46.9	90	
Fall Time <sup>2,3</sup>	$t_f$		-	12.3	23	
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}}=-15\text{V}, V_{\text{GS}}=0\text{V}, F=1\text{MHz}$	-	1250	2500	pF
Output Capacitance	$C_{\text{oss}}$		-	160	320	
Reverse Transfer Capacitance	$C_{\text{rss}}$		-	90	180	
<b>Source-Drain Ratings and Characteristics</b>						
Continuous Source Current	$I_s$	$V_{\text{GS}}=V_{\text{DS}}=0\text{V},$ Force Current	-	-	-30	A
Pulsed Source Current	$I_{\text{SM}}$		-	-	-60	A
Diode Forward Voltage	$V_{\text{SD}}$	$V_{\text{GS}}=0\text{V}, I_{\text{S}}=-1\text{A}, T_J=25^\circ\text{C}$	-	-	-1	V

Notes:

1. Repetitive rating: Pulsed width limited by maximum junction temperature.
2.  $V_{\text{DD}}=-25\text{V}, V_{\text{GS}}=-10\text{V}, L=0.1\text{mH}, I_{\text{AS}}=-33\text{A}$ , starting  $T_J=25^\circ\text{C}$ .
3. Pulse test: pulse width  $\leq 300\text{us}$ , duty cycle  $\leq 2\%$ .
4. Essentially independent of operating temperature.

## Typical Electrical and Thermal Characteristic Curves

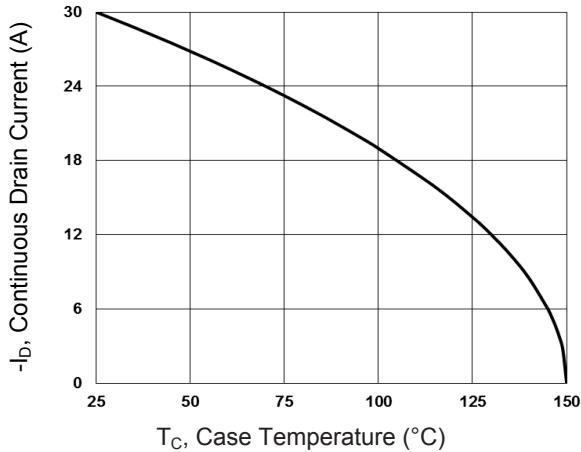


Figure 1. Continuous Drain Current Vs. T<sub>c</sub>

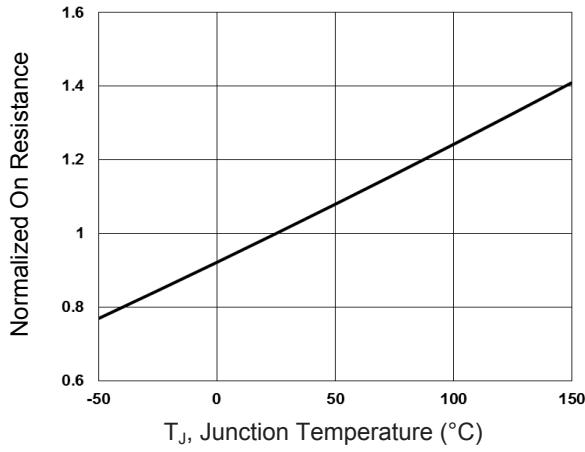


Figure 2. Normalized R<sub>DS(ON)</sub> Vs. T<sub>J</sub>

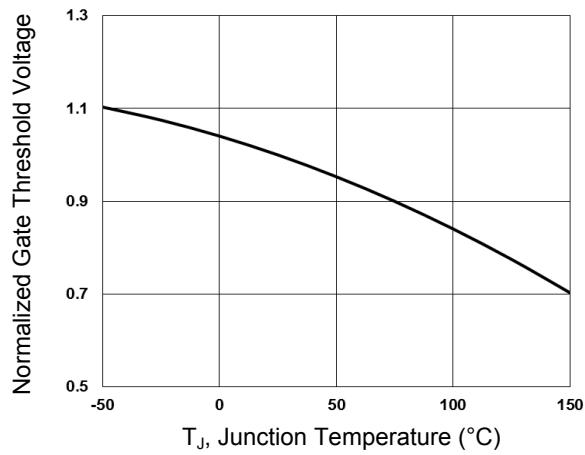


Figure 3. Normalized V<sub>th</sub> Vs. T<sub>J</sub>

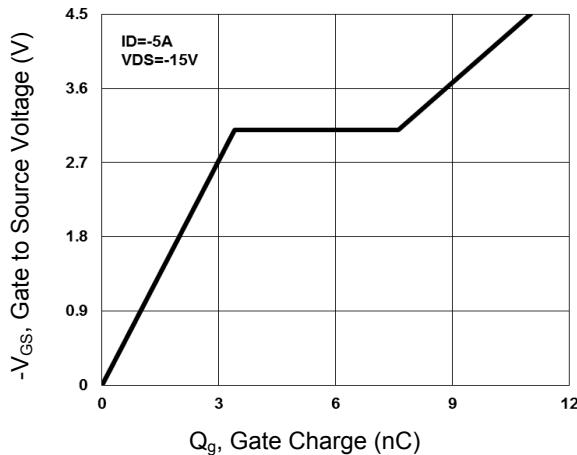


Figure 4. Gate Charge Waveform

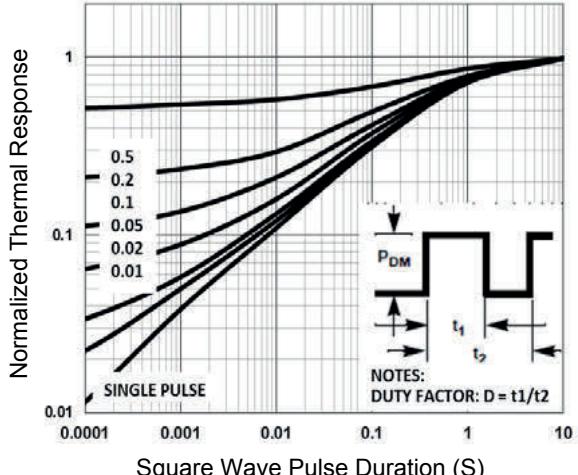


Figure 5. Normalized Transient Impedance

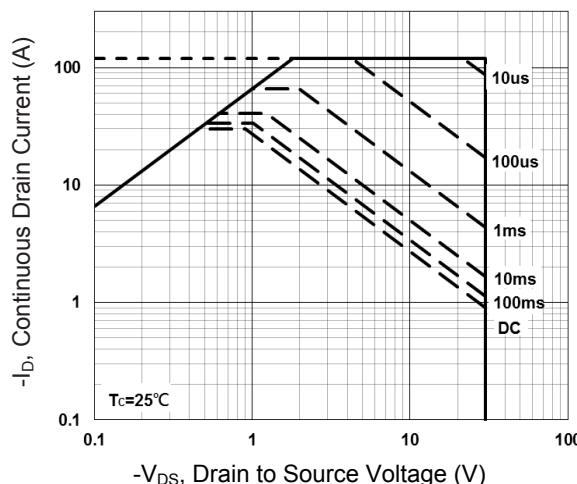
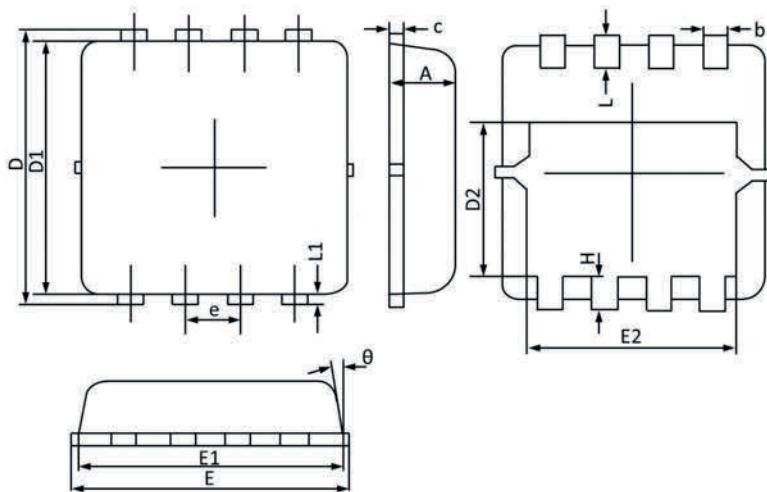


Figure 6. Maximum Safe Operation Area

### Package Outline Dimensions (PPAK3x3)



Symbol	Dimensions in Millimeters		Dimensions in Inches	
	Min	Max	Min	Max
A	0.70	0.90	0.028	0.035
b	0.25	0.35	0.010	0.014
c	0.10	0.25	0.004	0.010
D	3.05	3.50	0.120	0.138
D1	2.90	3.20	0.114	0.126
D2	1.35	1.95	0.053	0.077
E	3.00	3.40	0.118	0.134
E1	2.90	3.30	0.114	0.130
E2	2.35	2.60	0.093	0.102
e	0.65 BSC		0.026 BSC	
H	0.30	0.75	0.012	0.030
L	0.30	0.60	0.012	0.024
L1	0.06	0.20	0.002	0.008
θ	6°	14°	6°	14°